IN THE CLAIMS:

Cancel claims 22 through 40.

Please amend the claims as follows:

1. (Currently Amended) ~~A method of operating an~~ An automolding system comprising:
providing a substrate having a surface having a layer of resist on a portion thereof in the automolding system;
~~preheating the substrate;~~
~~forming a resist layer;~~
~~baking the substrate;~~ and
removing at least a portion of the layer of resist and at least a portion of the contaminants from the substrate using a laser in the automolding system.

2. (Currently Amended) The ~~method of operating an~~ automolding system of claim 1, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

3. (Currently Amended) The ~~method of operating an~~ automolding system of claim 1, further comprising:
~~placing the substrate in~~ a mold; and
encapsulating the substrate in the mold in the automolding system.

4. (Currently Amended) An ~~A method of using a~~ molding system comprising:
providing a substrate having a surface having a layer of resist on a portion thereof in the molding system;
~~preheating the substrate;~~
~~forming a resist layer;~~

~~baking the substrate; and~~

removing at least a portion of the layer of resist and contaminants from the substrate using a laser in the automolding system.

5. (Currently Amended) The ~~method of using a~~ molding system of claim 4, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

6. (Currently Amended) The ~~method of using a~~ molding system of claim 4, further comprising:

~~placing the substrate in~~ a mold in the molding system for ~~; and~~

encapsulating the substrate.

7. (Currently Amended) A ~~method for operating a~~ system for molding comprising:

providing a substrate having a surface having a layer of resist on a portion thereof for molding in the system;

~~preheating the substrate;~~

~~forming a resist layer;~~

~~baking the substrate; and~~

removing at least a portion of the layer of resist and some contaminants from the substrate using a laser in the automolding system.

8. (Currently Amended) The ~~method for operating a~~ system of claim 7, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

9. (Currently Amended) The ~~method for operating a~~ system of claim 7, further comprising:

~~placing the substrate in~~ a mold in the system for ~~; and~~

encapsulating the substrate.

10. (Currently Amended) An ~~A method for molding in an~~ automolding system comprising:

placing a substrate having a surface having a layer of resist on a portion thereof in the automolding system;

~~preheating the substrate;~~

~~forming a resist layer;~~

~~baking the substrate;~~ and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

11. (Currently Amended) The ~~method for molding in an~~ automolding system of claim 10, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

12. (Currently Amended) The ~~method for molding in an~~ automolding system of claim 10, further comprising:

~~placing the substrate in~~ a mold for ~~; and~~

encapsulating the substrate in the automolding system.

13. (Currently Amended) In a molding system ~~a method~~ comprising:

placing a substrate having a surface having a layer of resist on at least a portion thereof in the molding system;

~~preheating the substrate;~~

~~forming a resist layer;~~

~~baking the substrate;~~ and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

14. (Currently Amended) In the molding system of claim 13 ~~the method~~ , wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

15. (Currently Amended) In the molding system of claim 13 ~~the method~~ , further comprising:
~~placing the substrate in~~ a mold in the molding system~~; and~~
for encapsulating the substrate.

16. (Currently Amended) A ~~method in a~~ system for molding comprising:
placing a substrate having a surface having a layer of resist on at least a portion thereof for molding in the system;
~~preheating the substrate;~~
~~forming a resist layer;~~
~~baking the substrate;~~ and
removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

17. (Currently Amended) The ~~method of the~~ system of claim 16, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

18. (Currently Amended) The ~~method of the~~ system of claim 16, further comprising:
~~placing the substrate in~~ a mold in the system~~; and~~ for
encapsulating the substrate.

19. (Currently Amended) An ~~A method for using an~~ automolding system having a cleaning apparatus comprising:
introducing a substrate having a surface having a portion thereof covered with a layer of resist in the automolding system;
~~preheating the substrate;~~
~~forming a resist layer;~~
~~baking the substrate~~; and

removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system.

20. (Currently Amended) The ~~method for using an~~ automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

21. (Currently Amended) The ~~method for using an~~ automolding system of claim 19, further comprising:

~~placing the substrate in~~ a mold~~; and~~ for

encapsulating the substrate in the automolding system.

22 through 40 (Canceled)